

RELIABILITY REPORT  
FOR  
MAX3580ETJ+  
PLASTIC ENCAPSULATED DEVICES

January 19, 2009

**MAXIM INTEGRATED PRODUCTS**

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<b>Approved by</b>
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## Conclusion

The MAX3580ETJ+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

## Table of Contents

<b>I. ....Device Description</b>	<b>V. ....Quality Assurance Information</b>
<b>II. ....Manufacturing Information</b>	<b>VI. ....Reliability Evaluation</b>
<b>III. ....Packaging Information</b>	<b>IV. ....Die Information</b>
<b>.....Attachments</b>	

### I. Device Description

#### A. General

The MAX3580 fully integrated, direct-conversion TV tuner is designed for Digital Video Broadcasting-Terrestrial (DVB-T) applications. The integrated tuner covers a 170MHz to 230MHz input frequency range for the VHF-III band and 470MHz to 878MHz for the UHF band. The MAX3580 direct-conversion tuner integrates an RF input switch and a multiband tracking filter, allowing low-power tuner-on-board applications without the cost and power-dissipation issues of dual-conversion tuner solutions. The zero-IF architecture eliminates the need for SAW filters by providing baseband I and Q outputs directly to the demodulator. In addition, DC-offset cancellation is implemented on-chip using a mixed-signal architecture to improve the second-order distortion performance and the dynamic range of the downstream digitizer and demodulator. The MAX3580 features dynamic gain control of more than 76dB and a typical midband noise figure of 4.7dB referred to the LNA input. The VCO architecture optimizes both in-band and wideband phase noise for OFDM applications where sensitivity to both 1kHz phase noise and wideband phase noise related to strong adjacents can be a problem. The MAX3580 communicates using a 2-wire serial bus. The device operates from a typical +3.3V power supply and dissipates 650mW. The MAX3580 is available in a small 32-pin thin QFN package (5mm x 5mm) with an exposed paddle. Electrical performance is guaranteed over the extended -40°C to +85°C temperature range.

**II. Manufacturing Information**

A. Description/Function:	Direct-Conversion TV Tuner
B. Process:	MB3
C. Number of Device Transistors:	
D. Fabrication Location:	California
E. Assembly Location:	ASAT China, UTL Thailand, Unisem Malaysia
F. Date of Initial Production:	July 21, 2006

**III. Packaging Information**

A. Package Type:	32-pin TQFN 5x5
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2440
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	47°C/W
K. Single Layer Theta Jc:	1.7°C/W
L. Multi Layer Theta Ja:	29°C/W
M. Multi Layer Theta Jc:	2.7°C/W

**IV. Die Information**

A. Dimensions:	105.12 X 99.21 mils
B. Passivation:	BCB
C. Interconnect:	2 x Aluminum/Cu (Cu = 0.5%), top layer 100% Cu
D. Backside Metallization:	None
E. Minimum Metal Width:	0.35 um
F. Minimum Metal Spacing:	0.35 um
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Saw

## V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4340 \times 96 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 11.2 \times 10^{-9}$$

$$\lambda = 11.2 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at <http://www.maxim-ic.com/>. Current monitor data for the MB3 Process results in a FIT Rate of 0.7 @ 25C and 11.5 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The WG27 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000 V per JEDEC JESD22-A114-D. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX3580ETJ+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	96	0
<b>Moisture Testing</b> (Note 2) 85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2) Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data